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September 2015

FDS89161LZ

Dual N-Channel Shielded Gate PowerTrench[®] MOSFET 100 V, 2.7 A, 105 m Ω

Features

- Shielded Gate MOSFET Technology
- Max $r_{DS(on)}$ = 105 m Ω at V_{GS} = 10 V, I_D = 2.7 A
- Max $r_{DS(on)}$ = 160 m Ω at V_{GS} = 4.5 V, I_D = 2.1 A
- High performance trench technology for extremely low r_{DS(on)}
- High power and current handling capability in a widely used surface mount package
- CDM ESD protection level > 2KV typical (Note 4)
- 100% UIL Tested
- RoHS Compliant

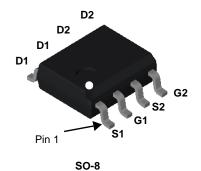


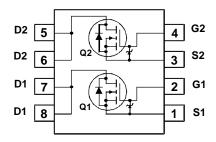
General Description

This N-Channel logic Level MOSFETs are produced using Fairchild Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. This process has been optimized for the on-state resisitance and yet maintain superior switching performance. G-S zener has been added to enhance ESD voltage level.

Application

■ DC-DC conversion





MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Param	neter		Ratings	Units	
V _{DS}	Drain to Source Voltage			100	V	
V _{GS}	Gate to Source Voltage			±20	V	
	Drain Current -Continuous			2.7		
ID	-Pulsed			15	Α	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	13	mJ	
P_{D}	Power Dissipation	T _C = 25 °C		31	14/	
	Power Dissipation	T _A = 25 °C	(Note1a)	1.6	W	
T _J , T _{STG}	Operating and Storage Junction Temper	ature Range		-55 to +150	°C	

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	78	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS89161LZ	FDS89161LZ	SO-8	13 "	12 mm	2500 units

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV_DSS	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		68		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V			1	μΑ
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±10	μΑ

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1	1.7	2.2	V
$\Delta V_{GS(th)}$ ΔT_J	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \mu A$, referenced to 25 °C		-6		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 2.7 \text{ A}$		81	105	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 2.1 \text{ A}$		110	160	mΩ
		$V_{GS} = 10 \text{ V}, I_D = 2.7 \text{ A}, T_J = 125 \text{ °C}$		140	182	
9 _{FS}	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 2.7 \text{ A}$		7.8		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 50 V, V _{GS} = 0 V, f = 1MHz	227	302	pF
C _{oss}	Output Capacitance		44	58	pF
C _{rss}	Reverse Transfer Capacitance		3	4	pF
R_g	Gate Resistance		0.9		Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		$V_{DD} = 50 \text{ V}, I_{D} = 2.7 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$		3.8	10	ns
t _r	Rise Time	V _{DD} = 50 V, I _D = 2.			1.2	10	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 10 V, R _{GEN}			9.5	17	ns
t _f	Fall Time				1.6	10	ns
$Q_{g(TOT)}$	Total Gate Charge	V _{GS} = 0 V to 10 V			3.8	5.3	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to 5 V}$			2.1	2.9	nC
Q_{gs}	Gate to Source Charge		$I_D = 2.7 A$		0.7		nC
Q _{gd}	Gate to Drain "Miller" Charge				0.7		nC

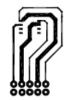
Drain-Source Diode Characteristics

V _{SD} Source to Drain D	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2.7 \text{ A}$	(Note 2)	0.8	1.3	\/
	Source to Drain Diode Forward voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2 \text{ A}$	(Note 2)	0.8	1.2	V
t _{rr}	Reverse Recovery Time	$I_F = 2.7 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s}$		31	56	ns
Q _{rr}	Reverse Recovery Charge			20	36	nC

^{1.} R_{0JA} is determined with the device mounted on a 1in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0JC} is guaranteed by design while R_{0CA} is determined by the user's board design.



a) 78°C/W when mounted on a 1 in² pad of 2 oz copper



b) 135°C/W when mounted on a minimun pad

- Pulse Test: Pulse Width < 300µs, Duty cycle < 2.0%.
 Starting TJ = 25 °C, L = 0.3 mH, IAS =25 A, VDD = 27 V, VGS = 10V.
 The diode connected between gate and source serves only as protection against ESD. No gate overvoltage rating is implied.

Typical Characteristics (N-Channel) T_J = 25°C unless otherwise noted

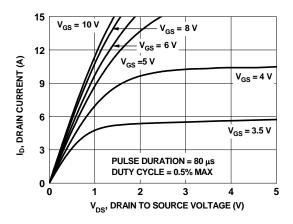


Figure 1. On-Region Characteristics

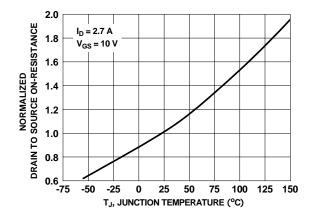


Figure 3. Normalized On-Resistance vs Junction Temperature

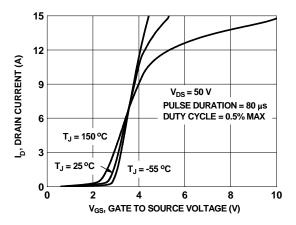


Figure 5. Transfer Characteristics

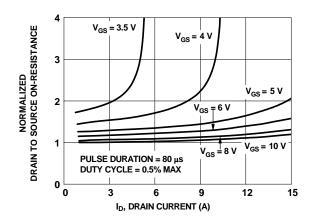


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

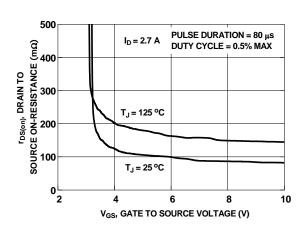


Figure 4. On-Resistance vs Gate to Source Voltage

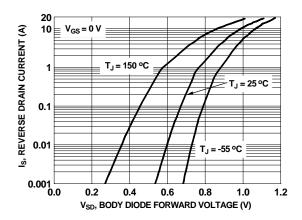


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics (N-Channel) T_J = 25°C unless otherwise noted

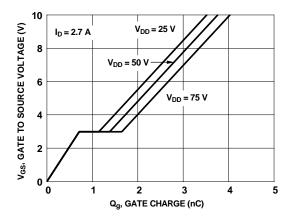


Figure 7. Gate Charge Characteristics

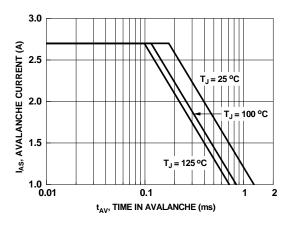


Figure 9. Unclamped Inductive Switching Capability

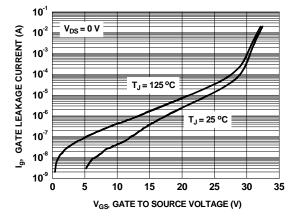


Figure 11. Gate Leakage Current vs Gate to Source Voltage

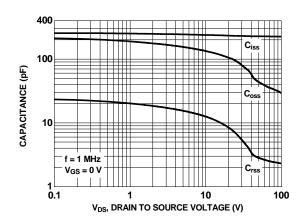


Figure 8. Capacitance vs Drain to Source Voltage

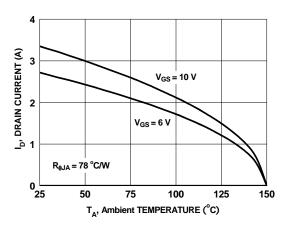


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

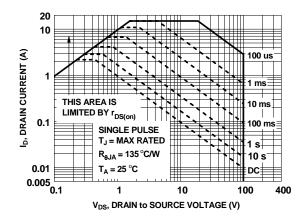


Figure 12. Forward Bias Safe Operating Area

Typical Characteristics (N-Channel) $T_J = 25$ °C unless otherwise noted

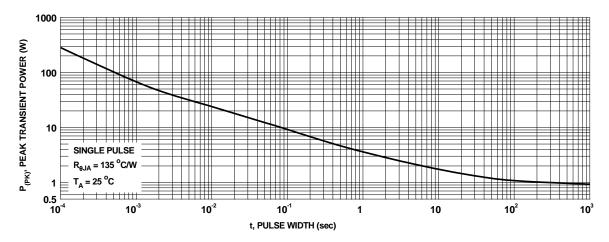


Figure 13. Single Pulse Maximum Power Dissipation

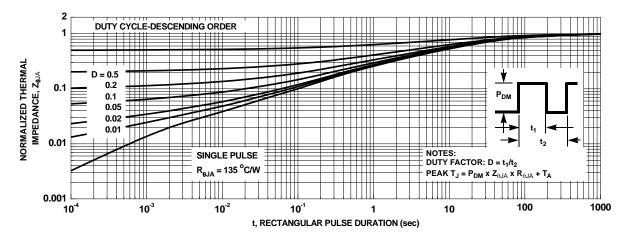


Figure 14. Junction-to-Ambient Transient Thermal Response Curve



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